

Maximum Ratings @T_A = 25°C unless otherwise specified

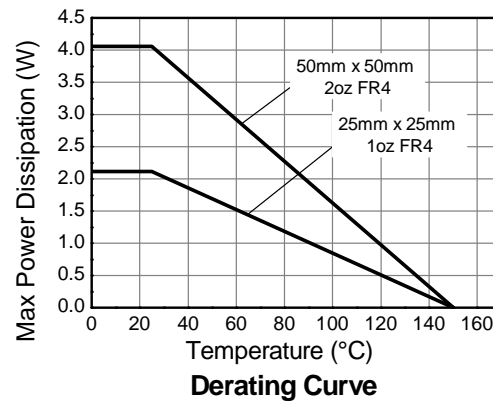
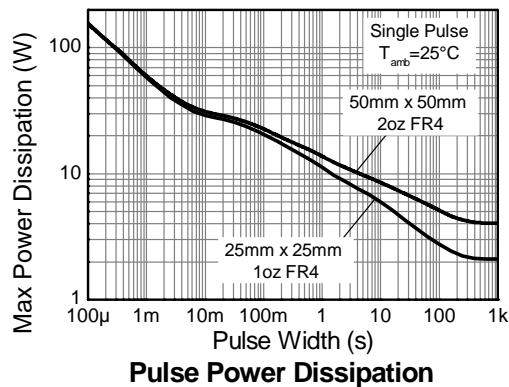
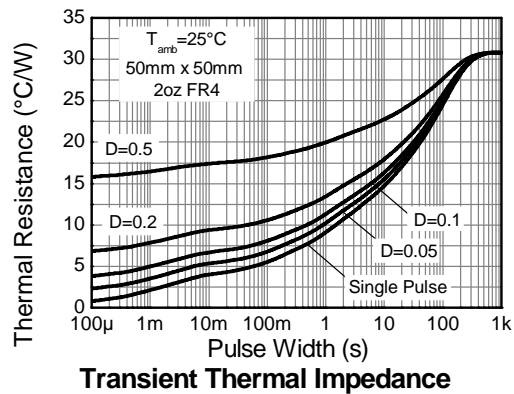
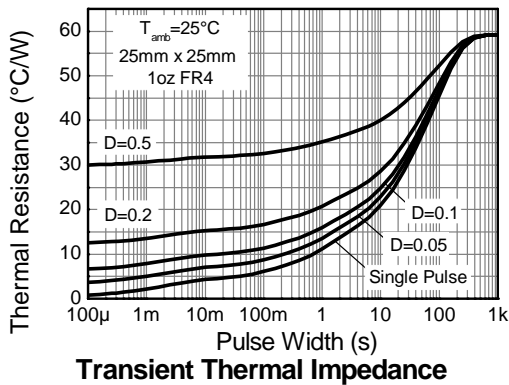
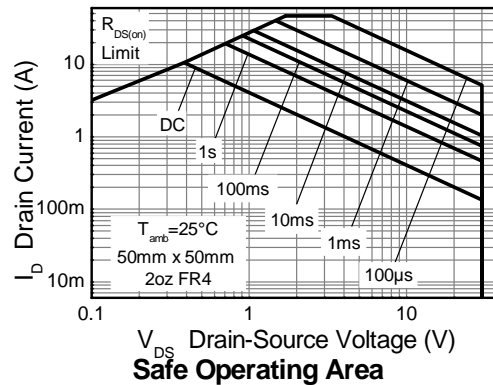
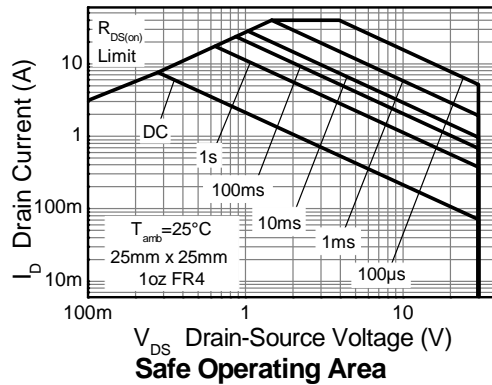
Characteristic			Symbol	Value	Unit
Drain-Source voltage			V _{DSS}	30	V
Gate-Source voltage			V _{GS}	±20	V
Continuous Drain current	V _{GS} = 10V	(Note 3)	I _D	14.4	A
		T _A =70°C (Note 3)		12.0	
		(Note 2)		9.78	
Pulsed Drain current	V _{GS} = 10V	(Note 4)	I _{DM}	46.5	A
Continuous Source current (Body diode)			I _S	12	A
Pulsed Source current (Body diode)			I _{SM}	46.5	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Power dissipation Linear derating factor	(Note 2)	P _D	4.1	W mW/°C
			32.5	
	(Note 3)		8.9	
			71.4	
Thermal Resistance, Junction to Ambient	(Note 5)	R _{θJA}	2.17	°C/W
			17.4	
	(Note 2)		30.8	
	(Note 3)		14.0	
Thermal Resistance, Junction to Lead	(Note 5)	R _{θJL}	57.6	°C/W
	(Note 6)		2.24	
Operating and storage temperature range		T _J , T _{STG}	-55 to 150	°C

- Notes:
2. For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 3. Same as note 2, except the device is measured at t ≤ 10 sec.
 4. Same as note 2, except the device is pulsed with D = 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.
 5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 6. Thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics

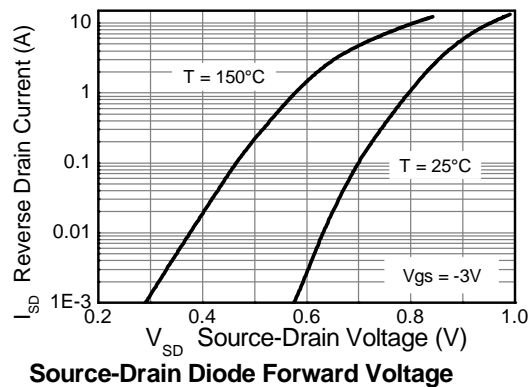
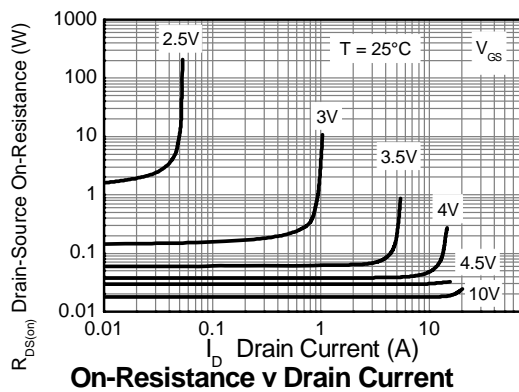
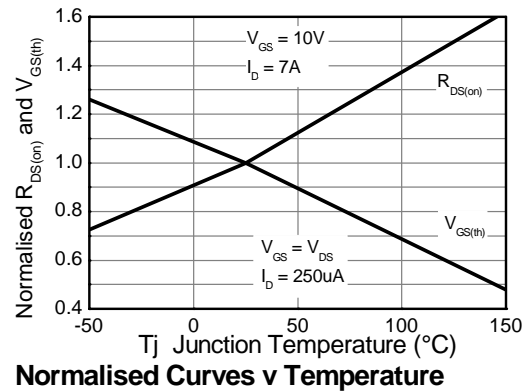
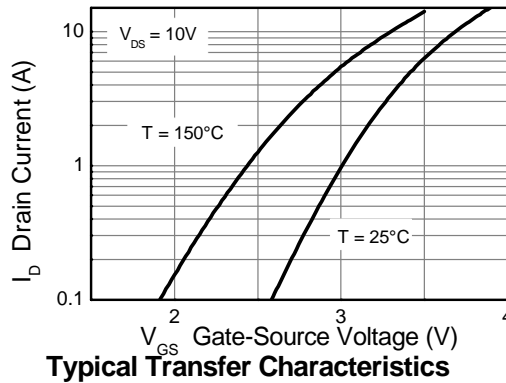
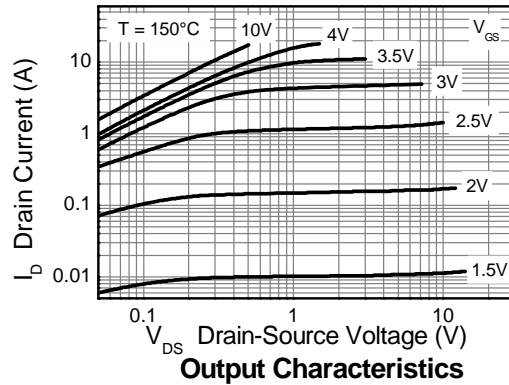
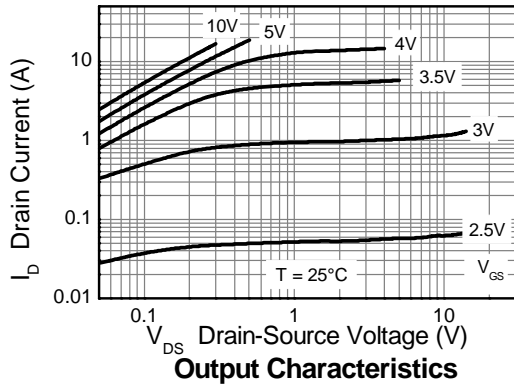


Electrical Characteristics @T_A = 25°C unless otherwise specified

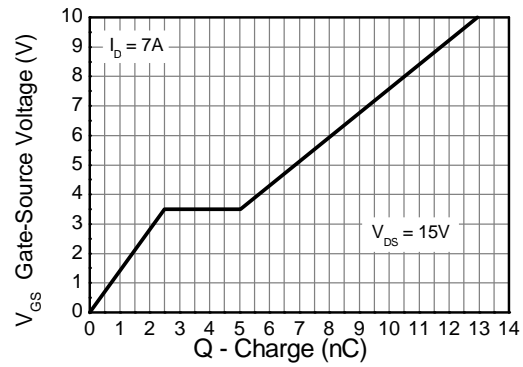
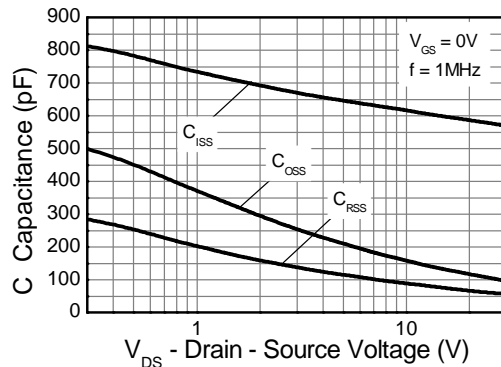
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	0.5	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	1.0	—	3.0	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 7)	R _{DS (ON)}	—	—	0.024	Ω	V _{GS} = 10V, I _D = 7.0A
				0.039		V _{GS} = 4.5V, I _D = 6.0A
Forward Transconductance (Notes 7 & 8)	g _{fs}	—	16.5	—	S	V _{DS} = 15V, I _D = 7.0A
Diode Forward Voltage (Note 7)	V _{SD}	—	0.82	1.2	V	I _S = 1.7A, V _{GS} = 0V
Reverse recovery time (Note 8)	t _{rr}		12	—	ns	I _S = 2.2A, di/dt= 100A/μs
Reverse recovery charge (Note 8)	Q _{rr}	—	4.8	—	nC	
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iSS}	—	608	—	pF	V _{DS} = 15V, V _{GS} = 0V f= 1MHz
Output Capacitance	C _{oSS}	—	132	—	pF	
Reverse Transfer Capacitance	C _{rSS}	—	71	—	pF	
Total Gate Charge	Q _g	—	12.9	—	nC	V _{DS} = 15V, V _{GS} = 10V I _D = 7A
Gate-Source Charge	Q _{gs}	—	2.5	—	nC	
Gate-Drain Charge	Q _{gd}	—	2.5	—	nC	
Turn-On Delay Time (Note 9)	t _{D(on)}	—	2.9	—	ns	V _{DD} = 15V, V _{GS} = 10V I _D = 1A, R _G ≐ 6.0Ω
Turn-On Rise Time (Note 9)	t _r	—	3.3	—	ns	
Turn-Off Delay Time (Note 9)	t _{D(off)}	—	16	—	ns	
Turn-Off Fall Time (Note 9)	t _f	—	8	—	ns	

- Notes:
7. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%
 8. For design aid only, not subject to production testing.
 9. Switching characteristics are independent of operating junction temperatures.

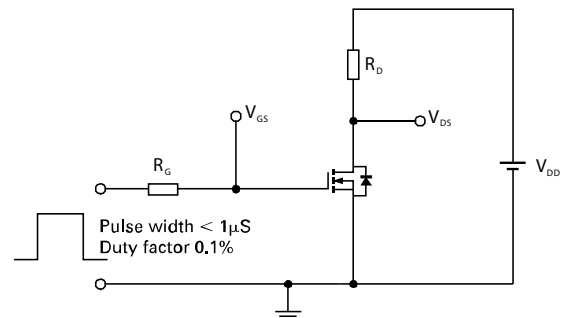
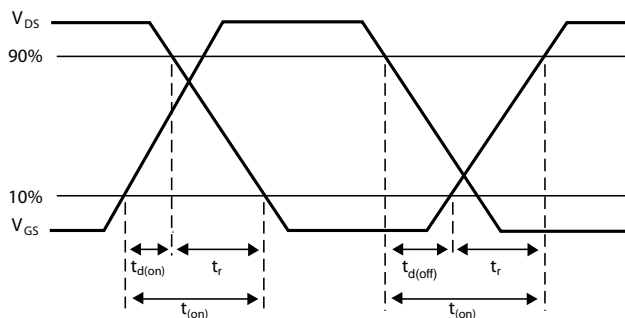
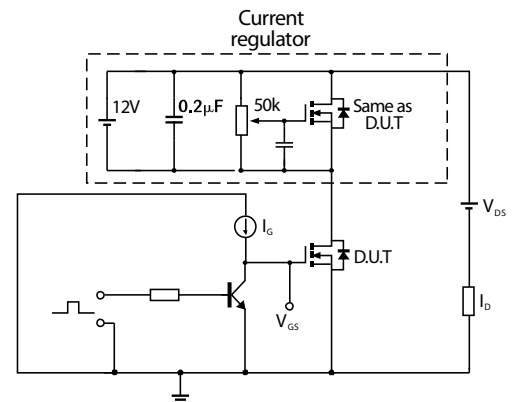
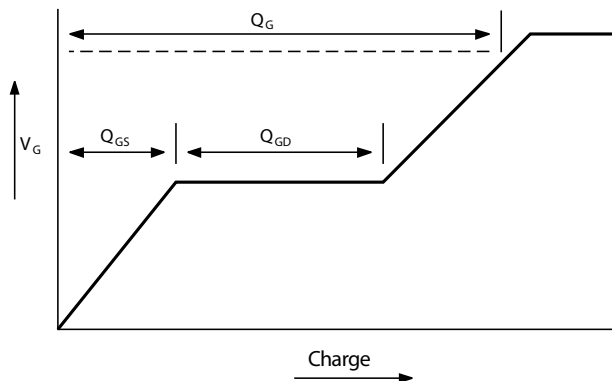
Typical Characteristics



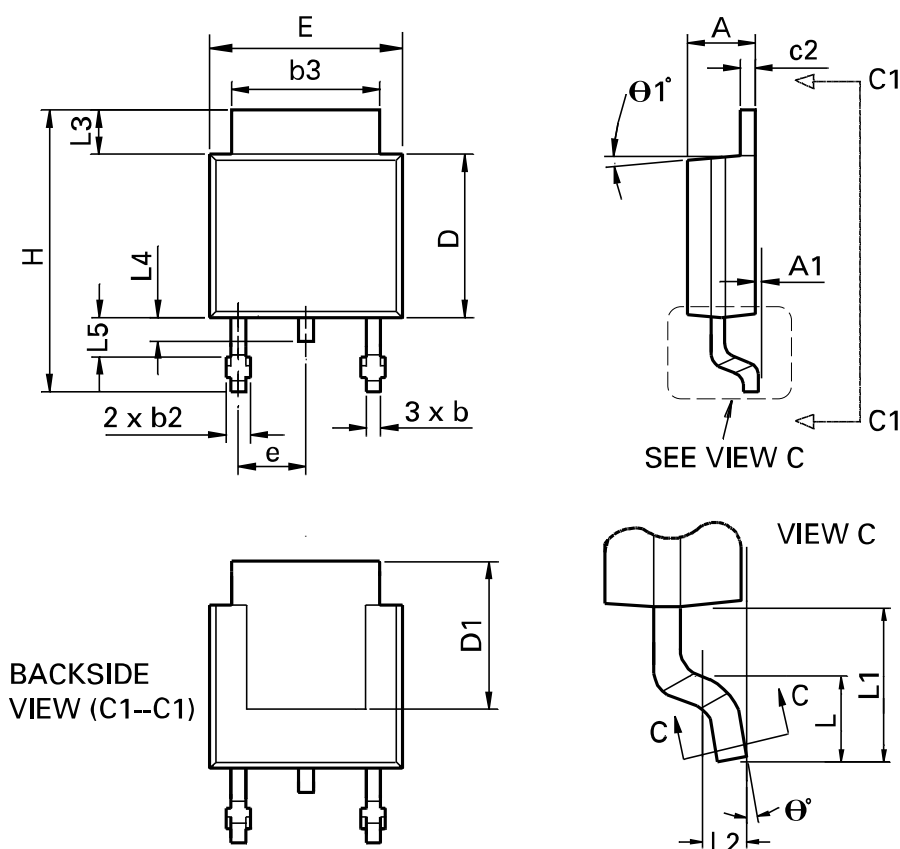
Typical Characteristics - continued



Test Circuits

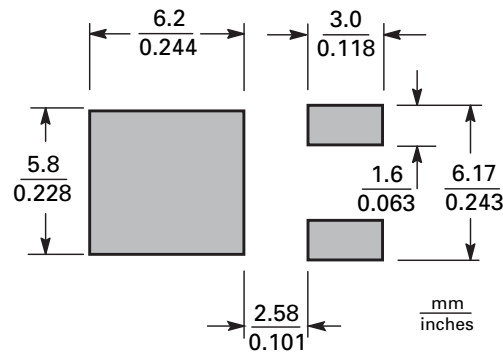


Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.086	0.094	2.18	2.39	e	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	H	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
c	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	θ_1	0°	10°	0°	10°
E	0.250	0.265	6.35	6.73	θ	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-

Suggested Pad Layout



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